

In the Abstract

Please replace the Abstract with the following rewritten paragraph:

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C.3 --A method for manufacturing an electronic device by placing within a die a first lead with an element placement pad, a second lead, and an electronic element placed on the element placement pad. The electronic element, the element placement pad, a part of the first lead, and a part of the second lead are sealed in a package by injecting a sealing resin in the die from a position on a longer side of the package, with the position being offset toward one shorter side thereof. The first lead is bent in an S shape, with a bending depth being at least as large as the thickness of the first lead. A thickness of the resin on a non-device side of the element placement pad is smaller than the bending depth.--

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